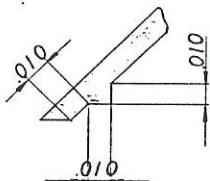
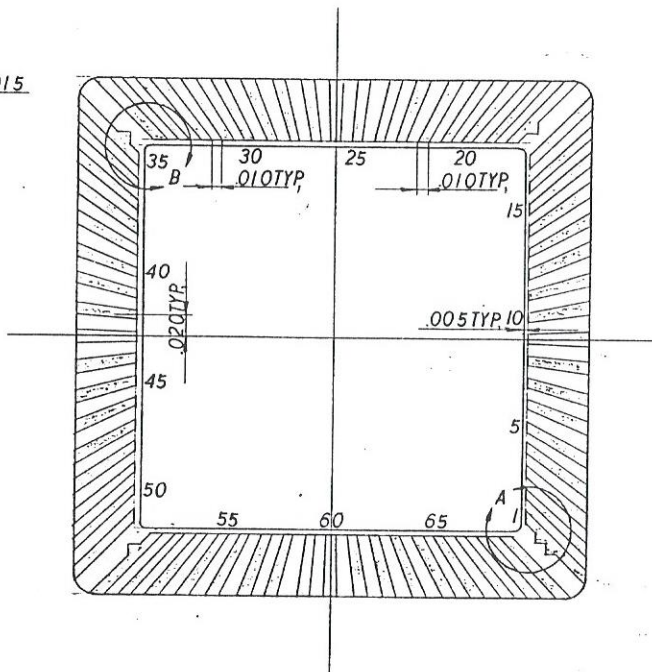


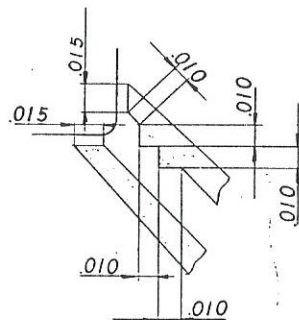
DETAIL-B



PINS 18, 35, 52



BONDING PATTERN



DETAIL-A

REVISIONS


NAME 68 PIN GRID ARRAY PACKAGE	
SCALE 10:1	MATERIAL

TOLERANCES UNLESS OTHERWISE SPECIFIED
--

DRAWN <i>M. Shimada</i>	CHECKED <i>M. Shimada</i>
APPROVED	DATE JUN. 21 '84

CHANGE

DATE DRAWN CHECKED APPROVED

KYOCERA CORPORATION

KYOTO JAPAN

DWG. NO. KD-84403

2/3

WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

BONDING PAD	PIN No.
1	B 2
2	B 1
3	C 2
4	C 1
5	D 2
6	D 1
7	E 2
8	E 1
9	F 2
10	F 1
11	G 2
12	G 1
13	H 2
14	H 1
15	J 2
16	J 1
17	K 1
18	K 2
19	L 2
20	K 3
21	L 3
22	K 4
23	L 4

BONDING PAD	PIN No.
24	K 5
25	L 5
26	K 6
27	L 6
28	K 7
29	L 7
30	K 8
31	L 8
32	K 9
33	L 9
34	L 10
35	K 10
36	K 11
37	J 10
38	J 11
39	H 10
40	H 11
41	G 10
42	G 11
43	F 10
44	F 11
45	E 10
46	E 11

BONDING PAD	PIN No.
47	D 10
48	D 11
49	C 10
50	C 11
51	B 11
52	B 10
53	A 10
54	B 9
55	A 9
56	B 8
57	A 8
58	B 7
59	A 7
60	B 6
61	A 6
62	B 5
63	A 5
64	B 4
65	A 4
66	B 3
67	A 3
68	A 2

MODIFICATIONS


NAME 68 PIN GRID ARRAY PACKAGE	
SCALE	MATERIAL

TOLERANCES UNLESS OTHERWISE SPECIFIED
--

DRAWN <i>A. Nakamura</i>	CHECKED <i>M. Shimada</i>
APPROVED	DATE JUN. 21 '84